

APPROVAL SHEET

RFBPF Series – 2012(0805)- RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

Halogens Free Product

2.4 GHz ISM Band Working Frequency

P/N: RFBPF2012080AC2T00

*Contents in this sheet are subject to change without prior notice.

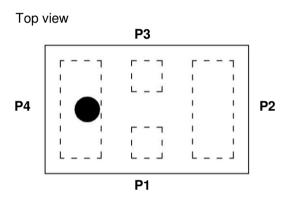
FEATURES

- 1. Miniature footprint: 2.0 X 1.2 X 0.8 mm³
- 2. Low Insertion Loss
- 3. High Rejection on GSM Bands
- 4. High attenuation on 2nd and 3rd harmonic suppressed
- 5. LTCC process

APPLICATIONS

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless LAN 802.11b/g/n, HomeRF
- 3. Internet of Things (IOT), Internet of Everything (IOE) applications.

CONSTRUCTION



| PIN | Connection | | | |
|-----|------------|--|--|--|
| 1 | Input | | | |
| 2 | GND | | | |
| 3 | Output | | | |
| 4 | GND | | | |

DIMENSIONS

| Figure | Symbol | Dimension (mm) |
|-------------|--------|----------------|
| | L | 2.00 ± 0.15 |
| _ L _ T_ | W | 1.25 ± 0.10 |
| | Т | 0.80 ± 0.10 |
| Top view ≥ | А | 0.15 ± 0.10 |
| • | В | 0.40 ± 0.10 |
| Side view | С | 0.30 ± 0.10 |
| | D | 0.30 ± 0.10 |
| A B C D | E | 0.15 ± 0.10 |
| Bottom view | F | 0.95 ± 0.10 |
| | G | 0.30 ± 0.10 |
| | Н | 0.35± 0.10 |

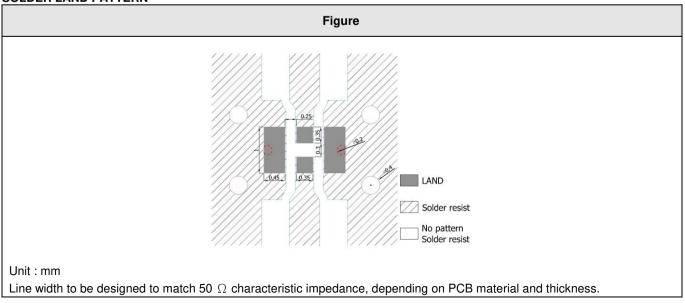
The thickness gap of PAD : 30um max.



ELECTRICAL CHARACTERISTICS

| Specification | | |
|--|--|--|
| 2412~2484 MHz | | |
| 1.35 dB max . | | |
| 2.0 max. | | |
| 50 Ω | | |
| 30 dB @ 804~ 828 MHz | | |
| 20 dB @ 1608~1656 MHz | | |
| 30 dB @ 3216~ 3312 MHz | | |
| 40 dB @ 4020~ 4140 MHz | | |
| 20 dB @ 4824~ 4968 MHz | | |
| 20 dB @ 5628 ~ 5796 MHz | | |
| 20 dB @ 6432 ~ 6624 MHz | | |
| 35 dB @ 7200 ~ 7500 MHz | | |
| 20 dB @ 7500 ~ 10000 MHz | | |
| -40°C ~ +85°C | | |
| | | |
| -S ₂₁ -S ₁₁ -S ₁₁ 3 4 5 6 7 8 9 10 Frequency (GHz) | | |
| | | |

SOLDER LAND PATTERN





RELIABILITY TEST

| Test item | Test condition / Test method | Specification |
|------------------------------|--|--|
| Solderability | *Solder bath temperature : $235 \pm 5^{\circ}$ C | At least 95% of a surface of each terminal |
| JIS C 0050-4.6 | *Immersion time : 2 ± 0.5 sec | electrode must be covered by fresh solder. |
| JESD22-B102D | Solder : Sn3Ag0.5Cu for lead-free | |
| Leaching | *Solder bath temperature : 260 ± 5°C | Loss of metallization on the edges of each |
| (Resistance to | *Leaching immersion time : 30 \pm 0.5 sec | electrode shall not exceed 25%. |
| dissolution of | Solder : SN63A | crodit due strait flot exceed 25%. |
| metallization) | | |
| IEC 60068-2-58 | | |
| Resistance to soldering heat | *Preheating temperature : 120~150℃, | No mechanical damage. |
| JIS C 0050-5.4 | 1 minute. | Electrical specification shall satisfy the |
| | *Solder temperature: 270±5°C | descriptions in electrical characteristics under |
| | *Immersion time: 10±1 sec | the operational temperature range within -40 |
| | Solder: Sp2Ag0 ECu for lead free | ~ 85°C. |
| | Solder: Sn3Ag0.5Cu for lead-free | Loss of metallization on the edges of each |
| | Measurement to be made after keeping at | electrode shall not exceed 25%. |
| | room temperature for 24±2 hrs | |
| Drop Test | *Height: 75 cm | No mechanical damage. |
| JIS C 0044 | *Test Surface: Rigid surface of concrete or | Electrical specification shall satisfy the |
| Customer's specification. | steel. | descriptions in electrical characteristics under |
| | | the operational temperature range within -40 |
| | *Times: 6 surfaces for each units; 2 times | ~ 85°C. |
| | for each side. | |
| Vibration | *Frequency: 10Hz~55Hz~10Hz(1min) | No mechanical damage. |
| JIS C 0040 | *Total amplitude: 1.5mm | Electrical specification shall satisfy the |
| | *Test times: 6hrs.(Two hrs each in three | descriptions in electrical characteristics under |
| | mutually perpendicular directions) | the operational temperature range within -40 |
| | maturally perpendicular directions) | ~ 85°C. |
| Adhesive Strength | | |
| of Termination | *Pressurizing force : | No remarkable damage or removal of the |
| JIS C 0051- 7.4.3 | 5N(≦0603) ; 10N(>0603) | termination. |
| | *Test time: 10±1 sec | |
| Bending test | The middle part of substrate shall be | No mechanical damage. |
| JIS C 0051- 7.4.1 | pressurized by means of the pressurizing rod | Electrical specification shall satisfy the |
| | at a rate of about 1 mm/s per second until the | descriptions in electrical characteristics under |
| | deflection becomes 1mm/s and then pressure | the operational temperature range within -40 |
| | shall be maintained for 5±1 sec. | ~ 85°C. |
| | Measurement to be made after keeping at | |
| | room temperature for 24±2 hours | |

| Approvai silect | | |
|---|--|---|
| Temperature cycle JIS C 0025 | 30±3 minutes at -40°C±3°C, 10~15 minutes at room temperature, 30±3 minutes at +85°C±3°C, 10~15 minutes at room temperature, Total 100 continuous cycles Measurement to be made after keeping at room temperature for 24±2 hrs | No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C. |
| High temperature JIS C 0021 | *Temperature: 85°C±2°C *Test duration: 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs | No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C. |
| Humidity (steady conditions) JIS C 0022 | *Humidity: 90% to 95% R.H. *Temperature: 40±2°C *Time: 1000+24/-0 hrs. Measurement to be made after keeping at room temperature for 24±2 hrs % 500hrs measuring the first data then 1000hrs data | No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C. |
| Low temperature JIS C 0020 | *Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs | No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C. |

SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

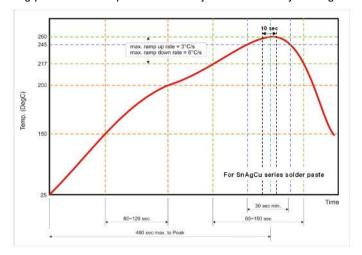


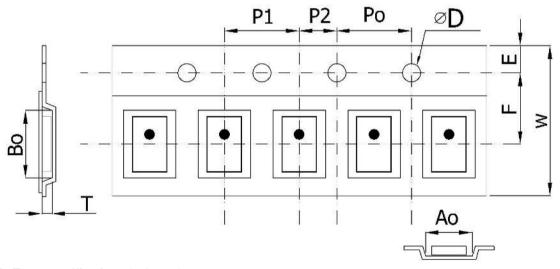
Fig 2. Infrared soldering profile

ORDERING CODE

| RF | BPF | 201208 | 0 | Α | C2T00 |
|-----------|---------------------|-------------------------|-------------------|---------------|---------------|
| Walsin | Product Code | Dimension code | Unit of dimension | Application | Specification |
| RF device | BPF: | Per 2 digits of Length, | 0 : 0.1 mm | A: 2.4GHz ISM | Design code |
| | Band Pass Filter | Width, Thickness | 1 : 1.0 mm | Band | |
| | | e.g. : 201208 : | | | |
| | | Length 20, | | | |
| | | Width 12, | | | |
| | | Thickness 08 | | | |

Minimum Ordering Quantity: 2000 pcs per reel.

PACKAGING

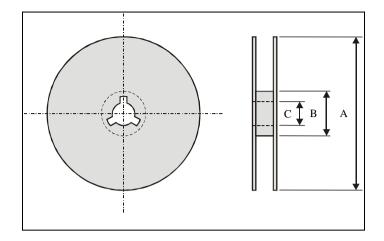


Plastic Tape specifications (unit :mm)

| Index | Ao | Во | ΦD | Т | W |
|----------------|-------------|-----------------|-------------|-----------------|-------------|
| Dimension (mm) | 1.42 ± 0.10 | 2.25 ± 0.10 | 1.55 ± 0.05 | 0.95 ± 0.10 | 8.0 ± 0.10 |
| Index | E | F | Po | P1 | P2 |
| Dimension (mm) | 1.75 ± 0.10 | 3.50 ± 0.05 | 4.00 ± 0.10 | 4.00 ± 0.10 | 2.00 ± 0.05 |



Reel dimensions



| Index | Α | В | С |
|----------------|--------|-------|-------|
| Dimension (mm) | Ф178.0 | Ф60.0 | Ф13.0 |

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.